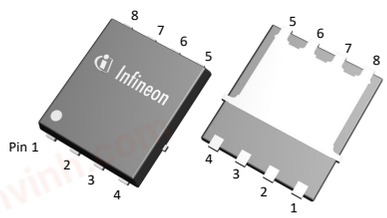
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MOSFET

OptiMOS™ 5 Power-Transistor, 100 V

PG-TDSON-8



Features

- Optimized for high performance SMPS, e.g. sync. Rec.
- 100% avalanche tested
- Superior thermal resistance
- N-channel, logic level
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product validation

Fully qualified according to JEDEC for Industrial Applications

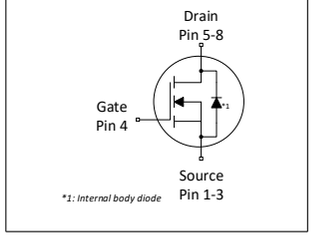


Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(on),max}$	3.4	mΩ
I_D	156	A
Q_{oss}	91	nC
Q_G(0V..4.5V)	37	nC

Type / Ordering Code	Package	Marking	Related Links
BSC034N10LS5	PG-TDSON-8	034N10LS	-

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1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current[1]	I_D	- - -	- - -	156 99 20	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=10V,T_A=25°C,R_{thJA}=50°C/W[2]
Pulsed drain current[3]	$I_{D,pulse}$	-	-	624	A	T_A=25 °C
Avalanche energy, single pulse[4]	E_{AS}	-	-	301	mJ	I_D=50 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	- -	- -	156 2.5	W	T_C=25 °C T_A=25 °C, R_{thJA}=50 °C/W[3]
Operating and storage temperature	T_j, T_{stg}	-55	-	150	°C	IEC climatic category; DIN IEC 68-1: 55/150/56

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	0.5	0.8	°C/W	-
Device on PCB, 6 cm² cooling area[2]	R_{thJA}	-	-	50	°C/W	-

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.
[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.
[3] See Diagram 3 for more detailed information
[4] See Diagram 13 for more detailed information

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3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	1.1	1.7	2.3	V	V_{DS}=V_{GS}, I_D=115 µA
Zero gate voltage drain current	I_{DSS}	- -	0.1 10	1 100	µA	V_{DS}=100 V, V_{GS}=0 V, T_j=25 °C V_{DS}=100 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	- -	2.8 3.5	3.4 4.6	mΩ	V_{GS}=10 V, I_D=50 A V_{GS}=4.5 V, I_D=25 A
Gate resistance	R_G	-	1.5	2.3	Ω	-
Transconductance	g_{fs}	60	120	-	S	|V_{DS}|≥2|I_D|$R_{DS(on)max}$, I_D=50 A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	5000	6500	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Output capacitance[1)]	C_{oss}	-	770	1000	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Reverse transfer capacitance[1)]	C_{rss}	-	34	60	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	9.6	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=3 Ω
Rise time	t_r	-	10	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=3 Ω
Turn-off delay time	$t_{d(off)}$	-	40	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=3 Ω
Fall time	t_f	-	16.0	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=3 Ω

Table 6 Gate charge characteristics[2)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	14	-	nC	V_{DD}=50 V, I_D=50 A, V_{GS}=0 to 4.5 V
Gate charge at threshold	$Q_{g(th)}$	-	8	-	nC	V_{DD}=50 V, I_D=50 A, V_{GS}=0 to 4.5 V
Gate to drain charge[1)]	Q_{gd}	-	13	19	nC	V_{DD}=50 V, I_D=50 A, V_{GS}=0 to 4.5 V
Switching charge	Q_{sw}	-	18	-	nC	V_{DD}=50 V, I_D=50 A, V_{GS}=0 to 4.5 V
Gate charge total[1)]	Q_g	-	37	46	nC	V_{DD}=50 V, I_D=50 A, V_{GS}=0 to 4.5 V
Gate plateau voltage	$V_{plateau}$	-	2.9	-	V	V_{DD}=50 V, I_D=50 A, V_{GS}=0 to 4.5 V
Gate charge total, sync. FET	$Q_{g(sync)}$	-	61	-	nC	V_{DS}=0.1 V, V_{GS}=0 to 10 V
Output charge[1)]	Q_{oss}	-	91	121	nC	V_{DS}=50 V, V_{GS}=0 V

[1)] Defined by design. Not subject to production test.
[2)] See "Gate charge waveforms" for parameter definition

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Table 7 Reverse diode

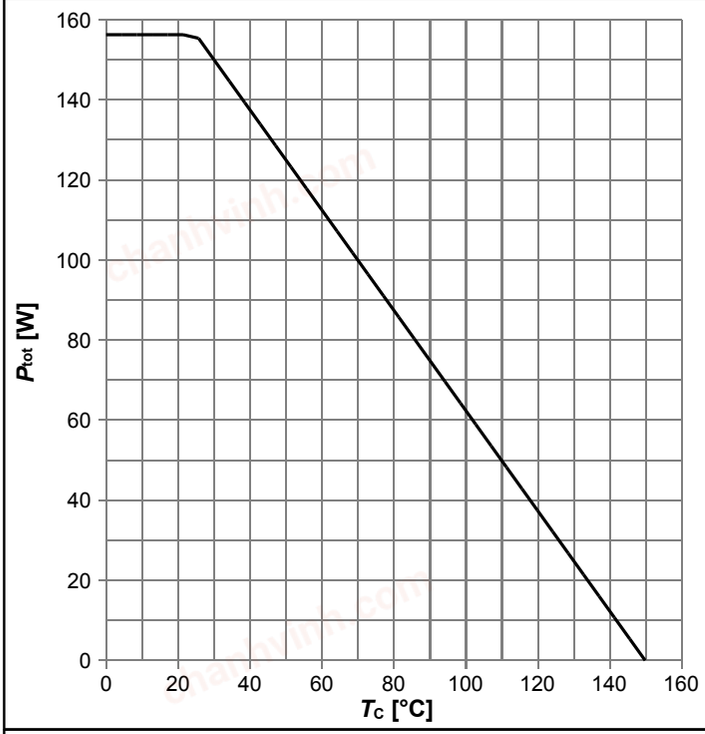
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	115	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	624	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.85	1.1	V	V_{GS}=0 V, I_F=50 A, T_j=25 °C
Reverse recovery time[1)]	t_{rr}	-	40	80	ns	V_R=50 V, I_F=50 A, di_F/dt=100 A/µs
Reverse recovery charge[1)]	Q_{rr}	-	42	84	nC	V_R=50 V, I_F=50 A, di_F/dt=100 A/µs

[1)] Defined by design. Not subject to production test.

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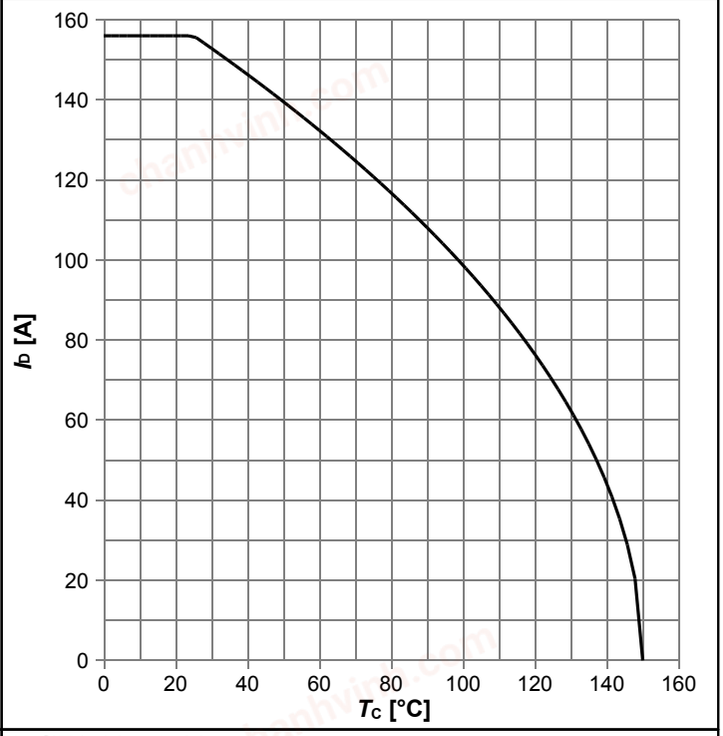
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



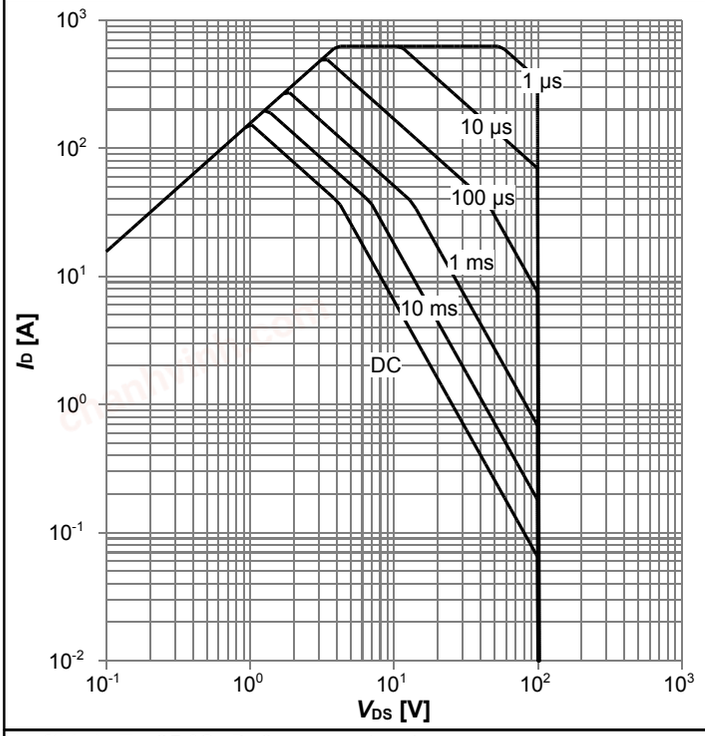
$P_{tot}=f(T_C)$

Diagram 2: Drain current



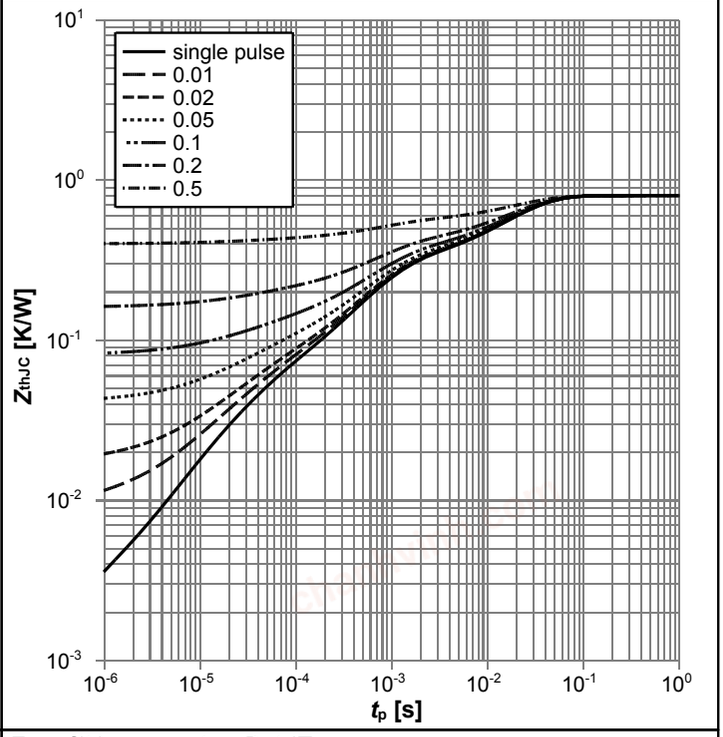
$I_D=f(T_C)$; $V_{GS}\geq 10$ V

Diagram 3: Safe operating area



$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$; parameter: t_p

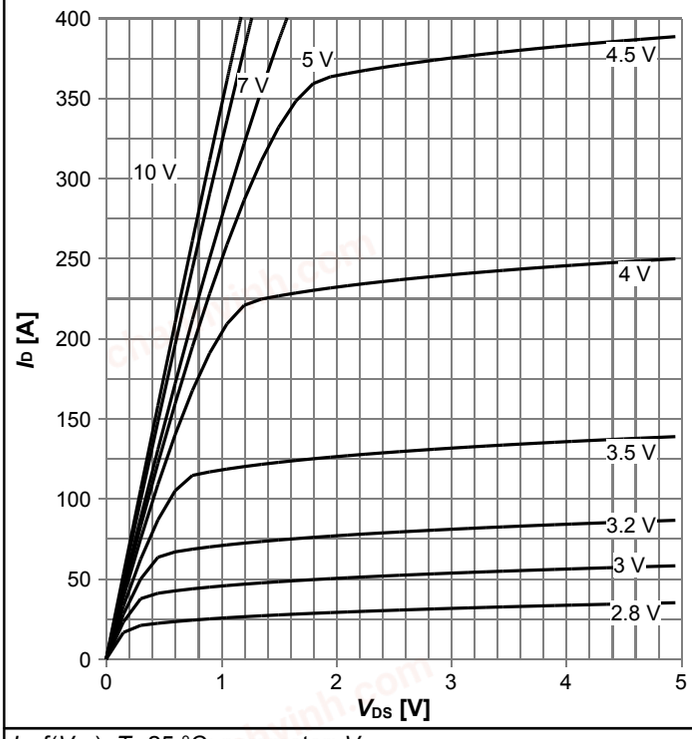
Diagram 4: Max. transient thermal impedance



$Z_{thJC}=f(t_p)$; parameter: $D=t_p/T$

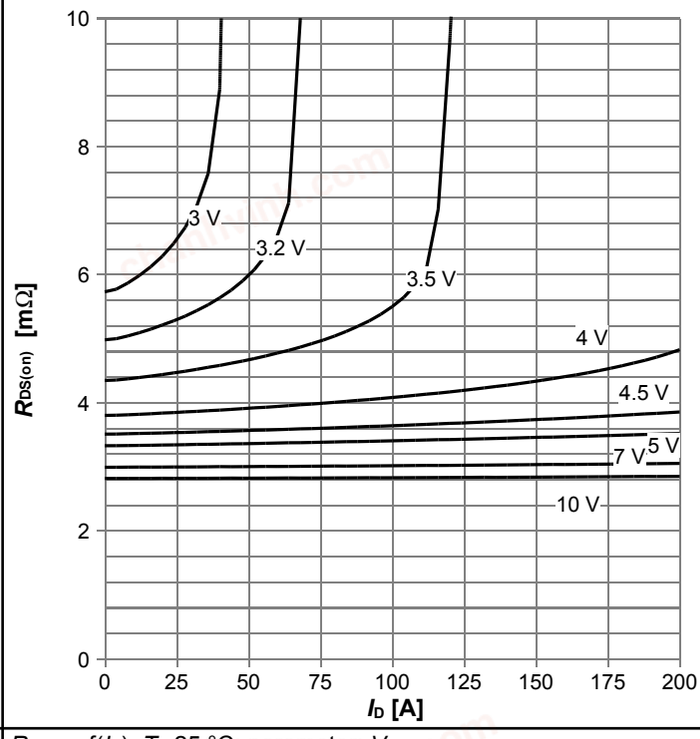
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Diagram 5: Typ. output characteristics



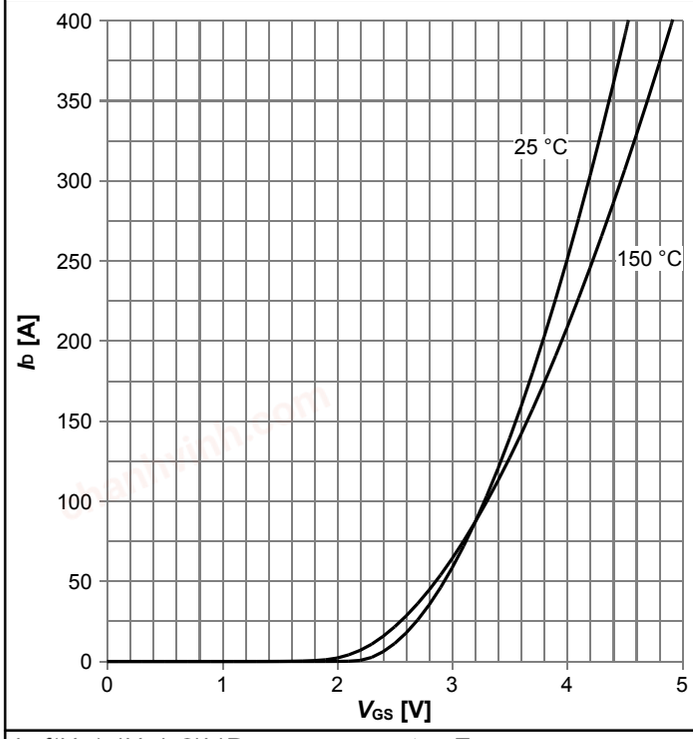
I_D=f(V_{DS}), T_j=25 °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



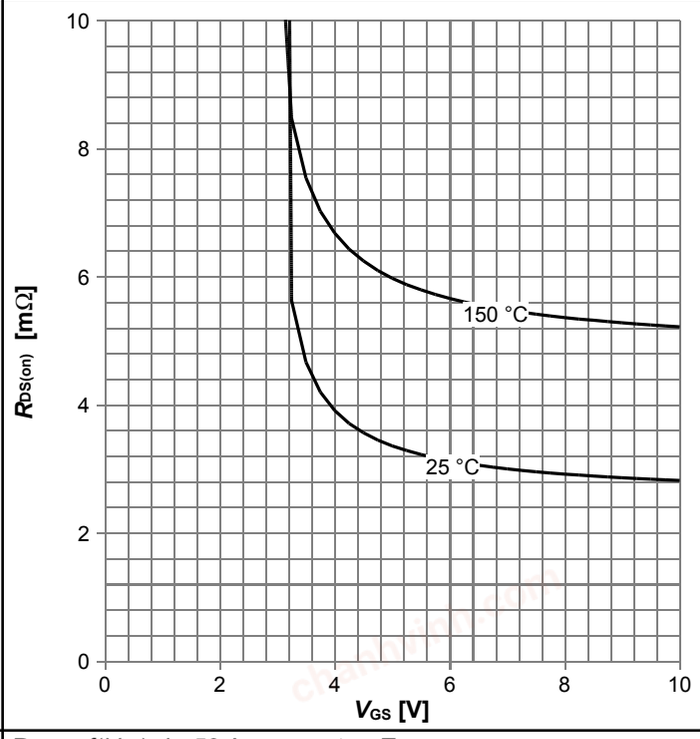
$R_{DS(on)}$=f(I_D), T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



I_D=f(V_{GS}), |V_{DS}|>2|I_D|$R_{DS(on)max}$; parameter: T_j

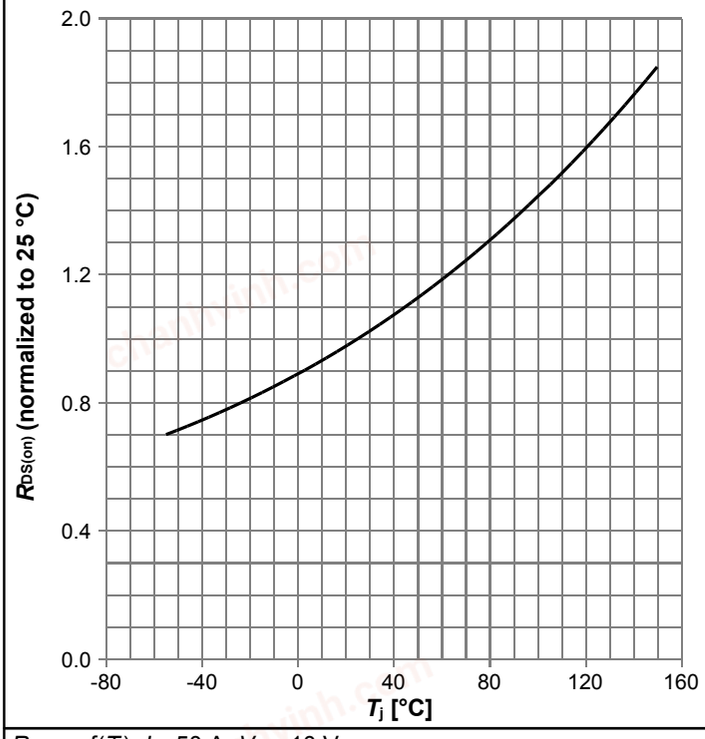
Diagram 8: Typ. drain-source on resistance



$R_{DS(on)}$=f(V_{GS}), I_D=50 A; parameter: T_j

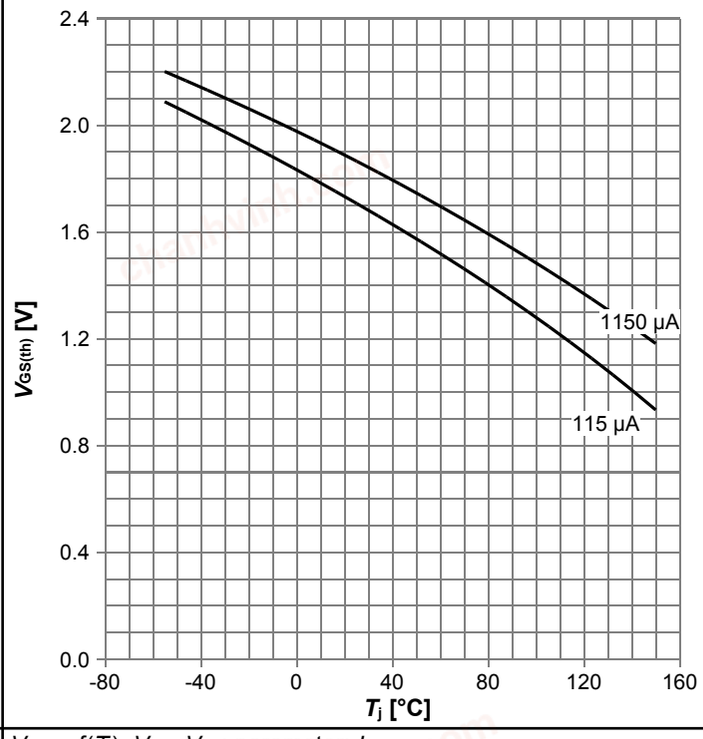
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Diagram 9: Normalized drain-source on resistance



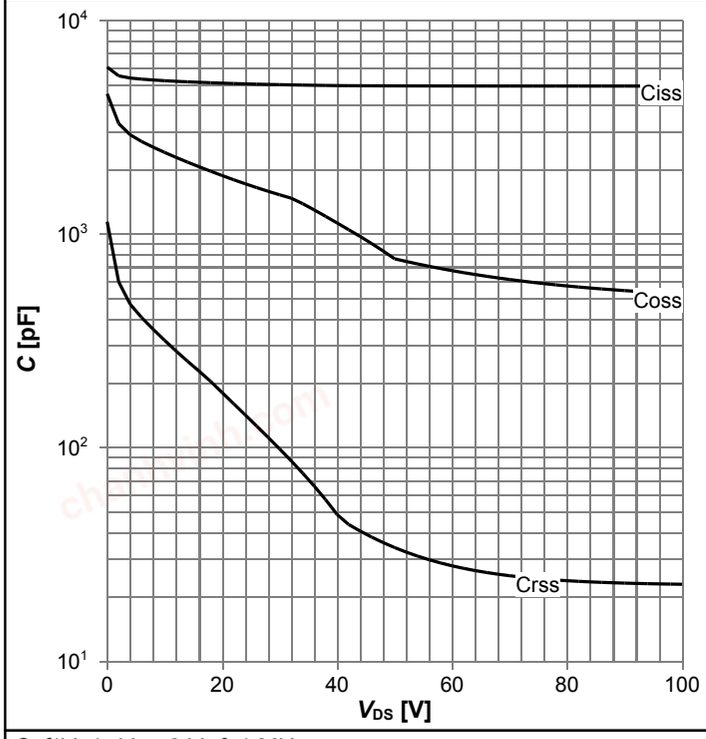
$R_{DS(on)}$=f(T_j), I_D=50 A, V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



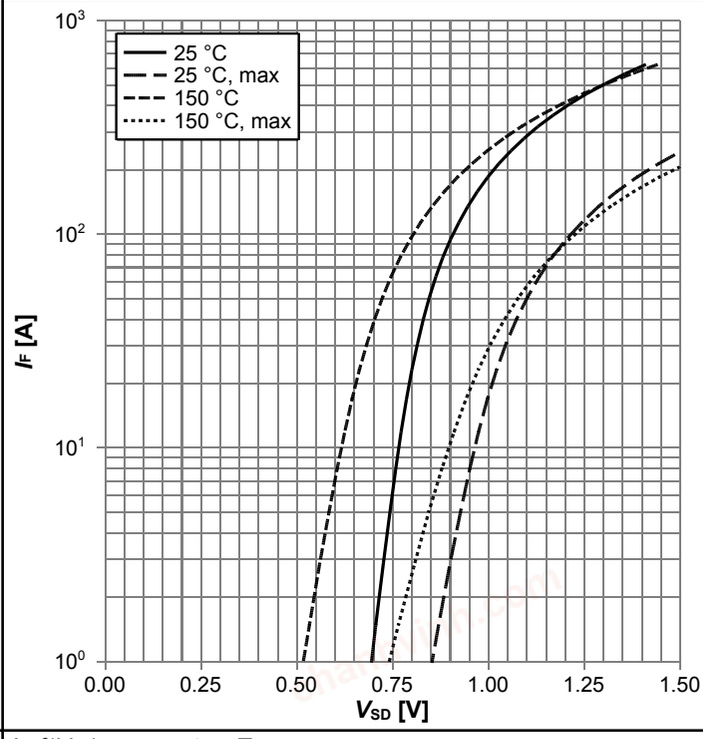
$V_{GS(th}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

Diagram 11: Typ. capacitances



C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

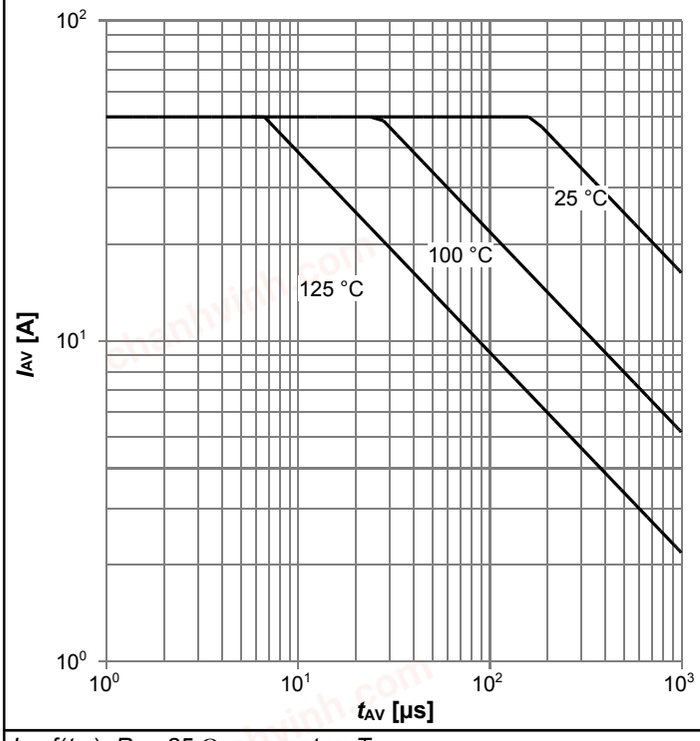
Diagram 12: Forward characteristics of reverse diode



I_F=f(V_{SD}); parameter: T_j

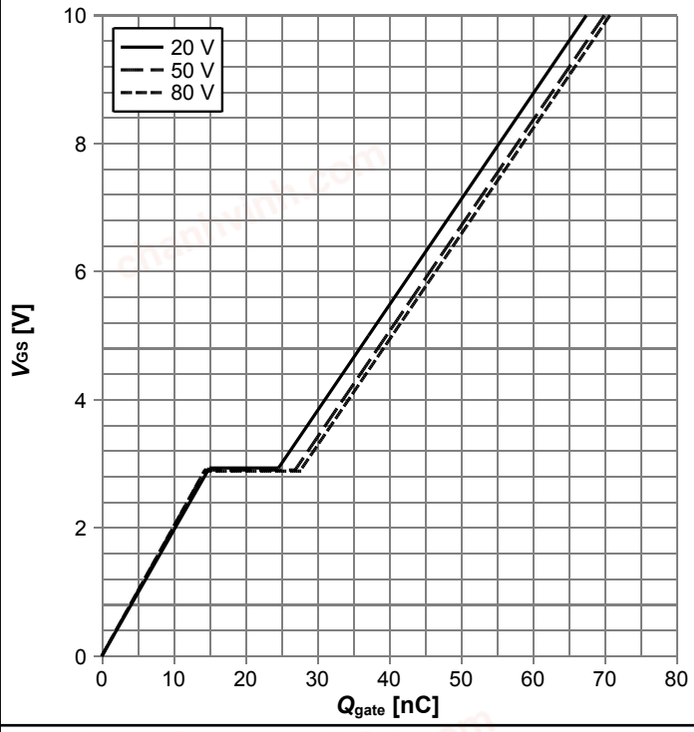
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Diagram 13: Avalanche characteristics



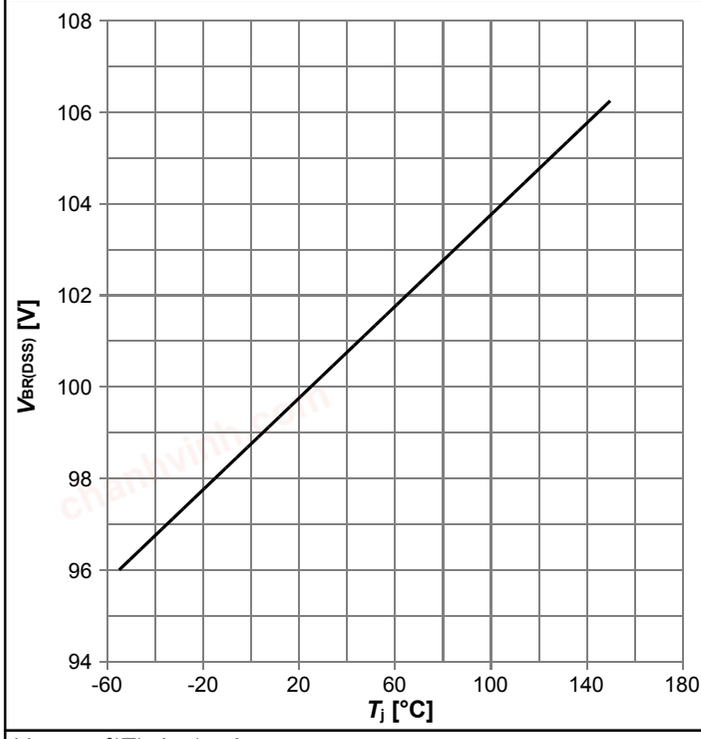
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j,start}$

Diagram 14: Typ. gate charge



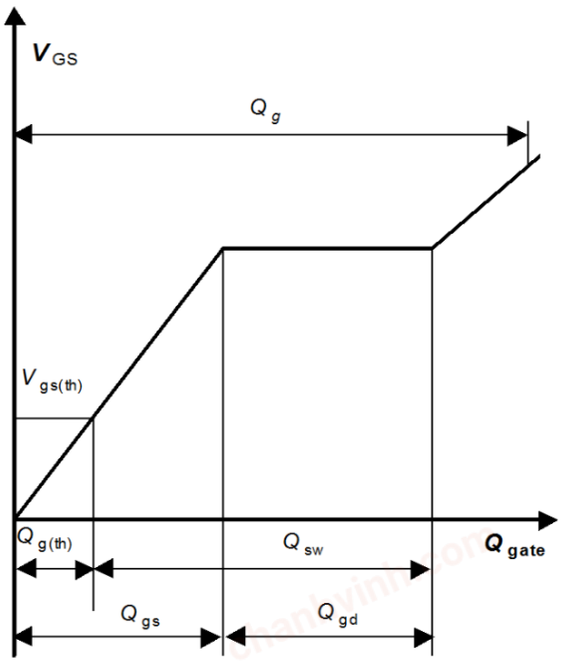
V_{GS}=f(Q_{gate}), I_D=50 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage



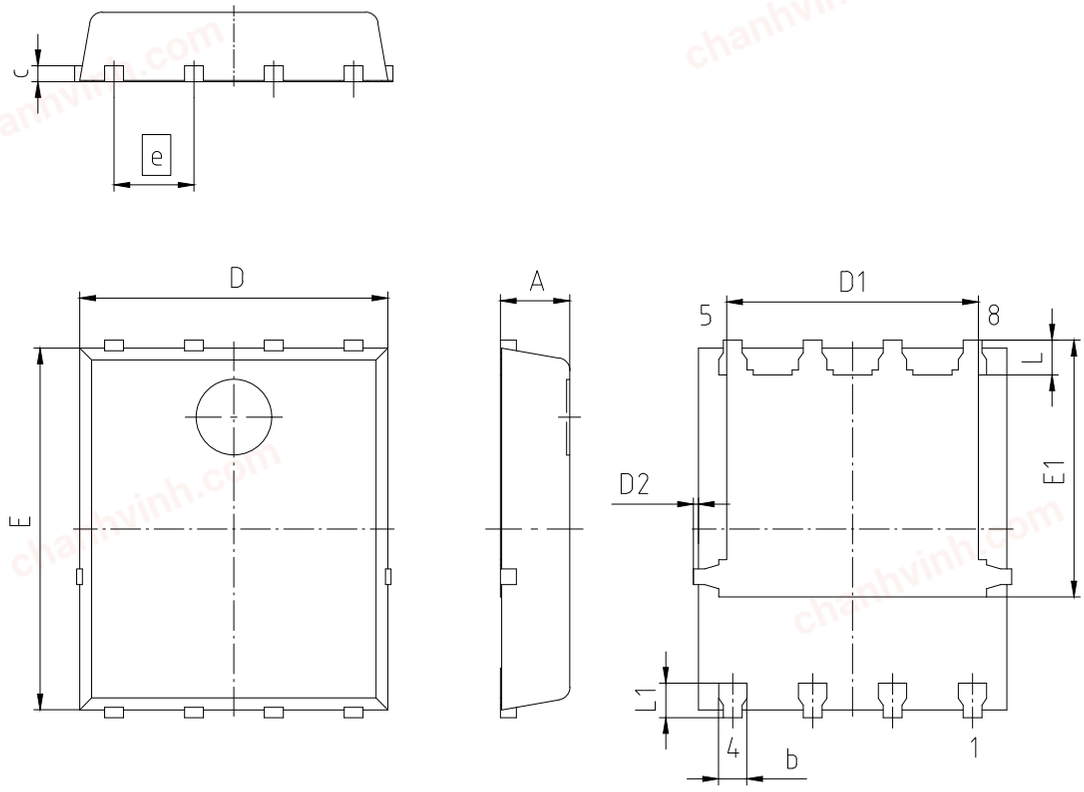
$V_{BR(DSS)}$=f(T_j); I_D=1 mA

Diagram Gate charge waveforms



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5 Package Outlines



PACKAGE - GROUP NUMBER:	PG-TDSON-8-U08	
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	0.90	1.20
b	0.34	0.54
c	0.15	0.35
D	4.80	5.35
D1	3.90	4.40
D2	0.00	0.22
E	5.70	6.10
E1	4.05	4.25
e	1.27	
L	0.45	0.65
L1	0.45	0.65

1) EXCLUDING MOLD FLASH
2) REMOVAL ON MOLD GATE
INTRUSION 0.1 MM
PROTRUSION 0.1 MM
3) ALL METAL SURFACES ARE PLATED,
EXCEPT AREA OF CUT

Figure 1 Outline PG-TDSON-8, dimensions in mm

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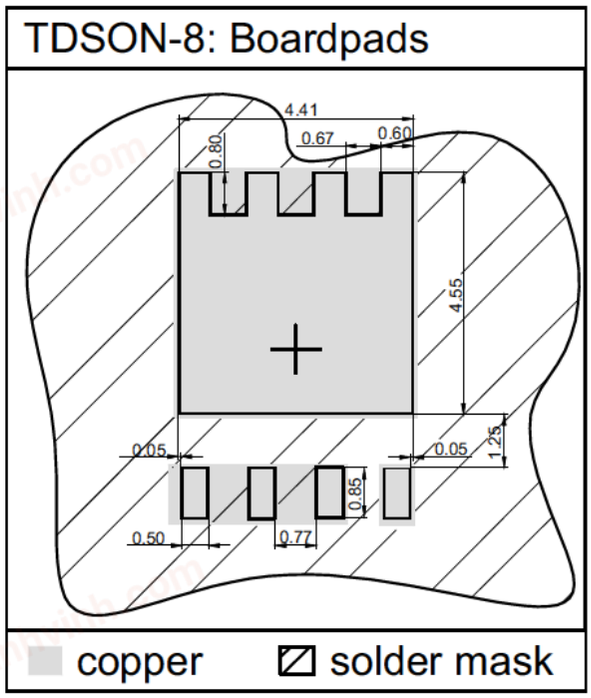


Figure 2 Outline Footprint (TDSON-8)

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Revision History

BSC034N10LS5

Revision: 2022-10-11, Rev. 2.4

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2016-09-30	Release of final version
2.1	2019-05-10	Update Diagrams 5, 8 and 9
2.2	2020-10-28	Update current rating
2.3	2022-01-31	Update Vsd typ and IS max
2.4	2022-10-11	Update outline drawing and footnotes

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